

VIGON® UC 160

Water-based cleaning agent for SMT stencil printer underside wipe systems



VIGON® UC 160 is a water-based cleaning agent designed to effectively remove solder paste residues from fine pitch stencil apertures in SMT printers. With low evaporative losses and effective wettability, product consumption is minimized and wipe cycles are reduced for optimal line operation.

Areas of application: Underside wipe		Additional product information:
Solder paste (unsoldered)	++	Technical Information 3: Overview of materials evaluated for compatibility

++ highly recommended, best results

+ recommended

0 possible

Technical Centers - ① America ② Europe ③ Malaysia ④ East China ⑤ South China
Cleaning Process Solutions under Production Floor Conditions



Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:
 Phone: +1 (703) 393-9880; Email: infousa@zestron.com

Advantages compared to other cleaners:

- Ideal for cleaning leaded and lead free solder paste from fine pitch stencil apertures during stencil underside wipe applications.
- Due to its water-based formulation, this cleaning agent evaporates significantly more slowly than IPA, limiting evaporative losses.
- No flash point and evaporates residue free.
- Water-based, surfactant-free cleaner with excellent material compatibility on all wetted parts (stencils & printers).
- No scaling or residue build up.
- Low odor.
- Halogen free.

Please refer to the material compatibility overview (Technical Information 3) prior to cleaning plastics.



Process	1. Solvent	2. Drying
SMT Printer	VIGON® UC 160	Vacuum Drying

Technical Data: VIGON® UC 160 as a ready-to-use mixture		
Density	(g/ccm) at 20°C/68°F	1.00
Surface tension	(mN/m) at 25°C/77°F	54.8
Boiling range	°C/°F	100-190/212-374
Flash point	°C/°F	None
pH-value	10g/l H ₂ O	Neutral
Vapor pressure	(mbar) at 20°C/68°F	Approx. 20
Cleaning temperature	°C/°F	Room Temperature
Application concentration	Ready to use	100%
Solubility in water		Soluble
HMS rating	Health-Flammability-Reactivity	0-0-0

Product Features		
	Extensively tested and suitable for cleaning of LF solder pastes	
		100% compliance with EU guidelines

Environmental, health and safety regulations:

- VIGON® UC 160 is water-based and biodegradable.
- The cleaning agent is free of any halogenated compounds.
- Refer to the MSDS for specific handling precautions and instructions.

Availability:

- VIGON® UC 160 is available as an easy-to-use solution in 1L, 5L and 25L containers and 200L drums.
- VIGON® UC 160 is a non-hazardous material.

Storage:

- Store VIGON® UC 160 in the original container at a temperature between 5-30°C/41-86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

- For stencil underside wipe cleaning in printers without vacuum drying, we recommend solvent based ZESTRON® SW.